

**Amendments to the Specification:**

Please replace the paragraph beginning at page 4, line 10, with the following rewritten paragraph:

- 5       -- Please refer to FIG. 4, which is a schematic illustration showing the cleaning system having an image sensor semi-package being cleaned. The image sensor semi-package is defined as a combination of a substrate 64 and a frame layer 66. A chamber 68 is formed between the substrate 64 and the frame layer 66. The substrate 64 is located within the cleaning room 62, and is mounted on the
- 10 rotating device 52, and the chamber 68 faces the ~~periphery wall 58~~ of the cleaning device 54. Therefore, the cleaner is ejected from the cleaning device 54 to the chamber 68 in a direction opposite to a direction of a centrifugal force of the combination of the substrate 64 and the frame layer 66, so that the chamber 68 of the combination may be cleaned by the cleaner. In this invention, the rotating
- 15 device 52 is configured to fix the combination of the substrate 64 and the frame layer 66 with the chamber 68 facing the cleaning device 54, and an interface I1 between the substrate 64 and the frame layer 66 is substantially perpendicular to an interface I2 between the rotating device 52 and the combination of the substrate 64 and the frame layer 66. Also, the chamber 68 has a bottom surface
- 20 68A facing the cleaning device 54, and an inner circumferential wall 68B connected to the bottom surface 68A, and the bottom surface 68A of the chamber 68 is substantially in parallel with an axis 52A of rotation of the rotating device 52. In addition, two combinations of the substrates and the frame layers are disposed on the rotating device 52 and opposite to each other. --

25